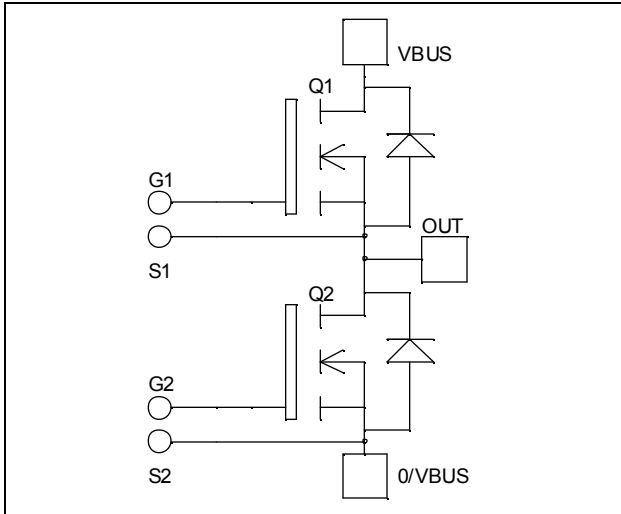


Phase leg MOSFET Power Module

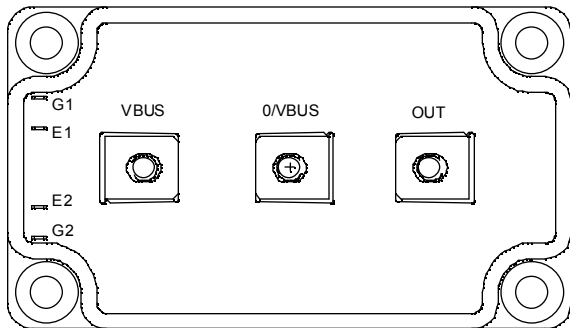
$V_{DSS} = 100V$
 $R_{DSon} = 2.25m\Omega$ typ @ $T_j = 25^\circ C$
 $I_D = 495A$ @ $T_c = 25^\circ C$


Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features


- Power MOS V[®] FREDFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Fast intrinsic diode
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration


Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	100	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	A
		$T_c = 80^\circ C$	
I_{DM}	Pulsed Drain current	1900	
V_{GS}	Gate - Source Voltage	± 30	V
R_{DSon}	Drain - Source ON Resistance	2.5	$m\Omega$
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$	1250
I_{AR}	Avalanche current (repetitive and non repetitive)	100	A
E_{AR}	Repetitive Avalanche Energy	50	mJ
E_{AS}	Single Pulse Avalanche Energy	3000	


CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 100V$			400	μA
		$V_{GS} = 0V, V_{DS} = 80V$			2000	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 200A$		2.25	2.5	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 10\text{mA}$	2		4	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			± 400	nA

Dynamic Characteristics

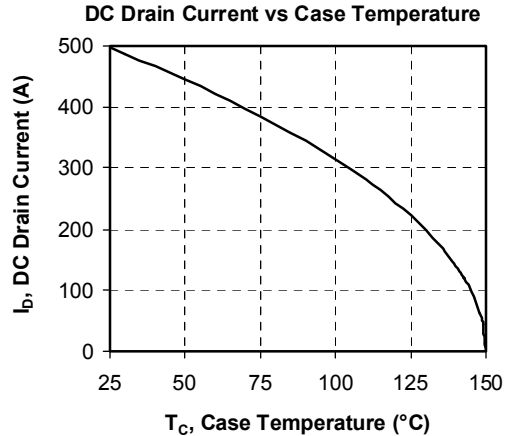
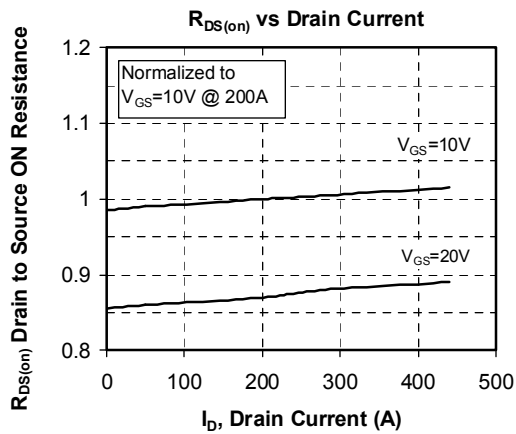
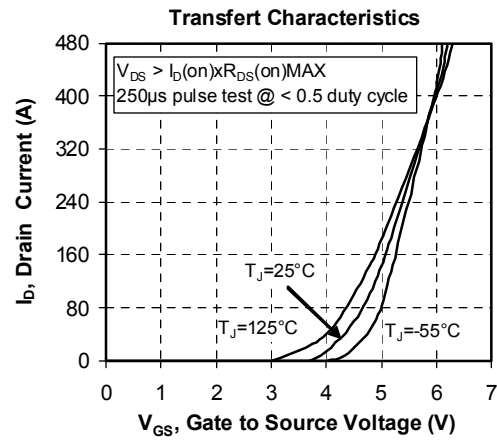
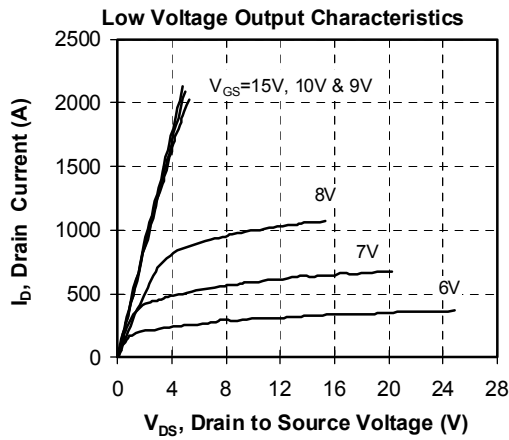
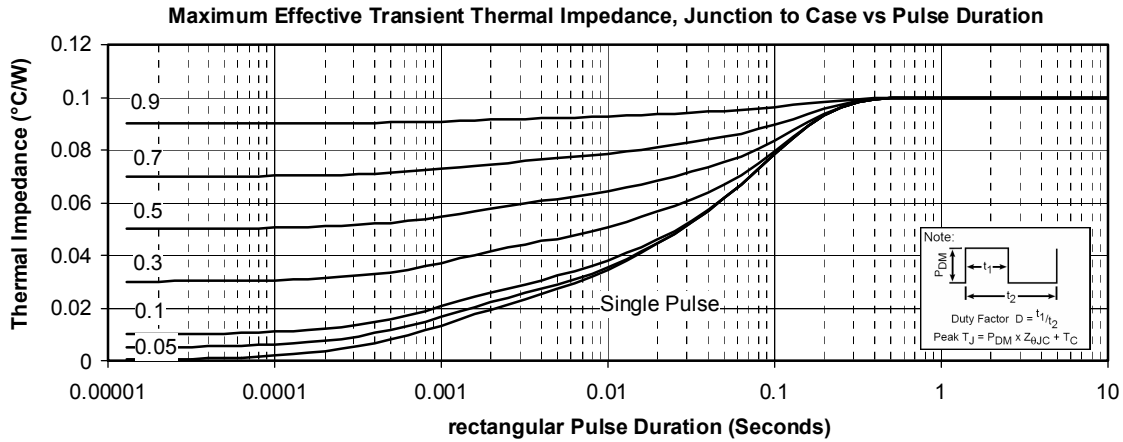
Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$		40		nF
C_{oss}	Output Capacitance	$V_{DS} = 25V$		15.7		
C_{rss}	Reverse Transfer Capacitance	$f = 1\text{MHz}$		5.9		
Q_g	Total gate Charge	$V_{GS} = 10V$		1360		nC
Q_{gs}	Gate – Source Charge	$V_{Bus} = 50V$		240		
Q_{gd}	Gate – Drain Charge	$I_D = 400A$		720		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C		160		ns
T_r	Rise Time	$V_{GS} = 15V$		240		
$T_{d(off)}$	Turn-off Delay Time	$V_{Bus} = 66V$		500		
T_f	Fall Time	$I_D = 400A$ $R_G = 1.25\Omega$		160		
E_{on}	Turn-on Switching Energy	Inductive switching @ 25°C		2.2		mJ
E_{off}	Turn-off Switching Energy	$V_{GS} = 15V, V_{Bus} = 66V$ $I_D = 400A, R_G = 1.25\Omega$		2.41		
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C		2.43		mJ
E_{off}	Turn-off Switching Energy	$V_{GS} = 15V, V_{Bus} = 66V$ $I_D = 400A, R_G = 1.25\Omega$		2.56		

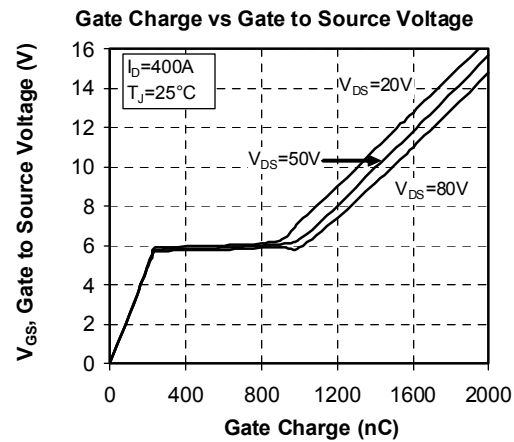
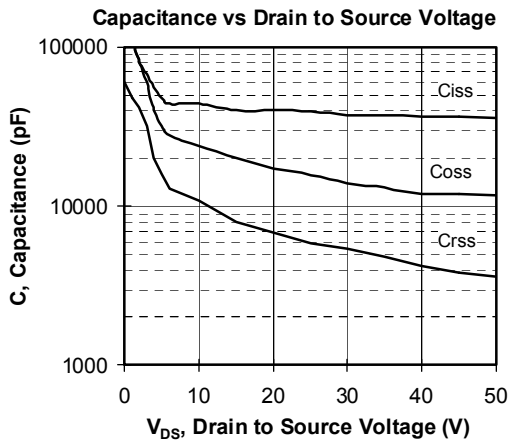
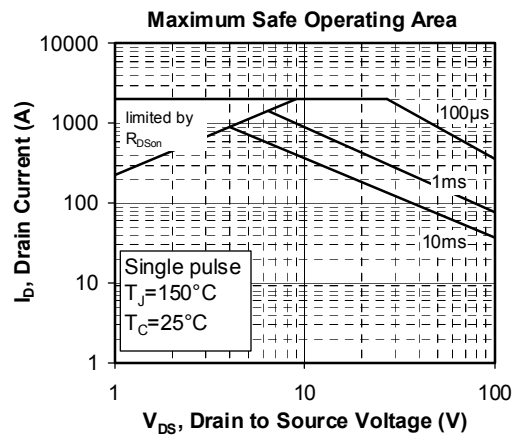
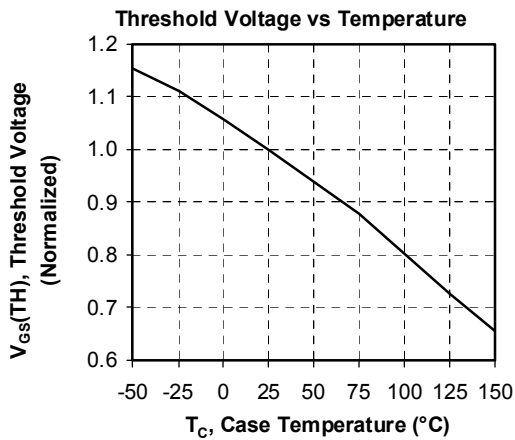
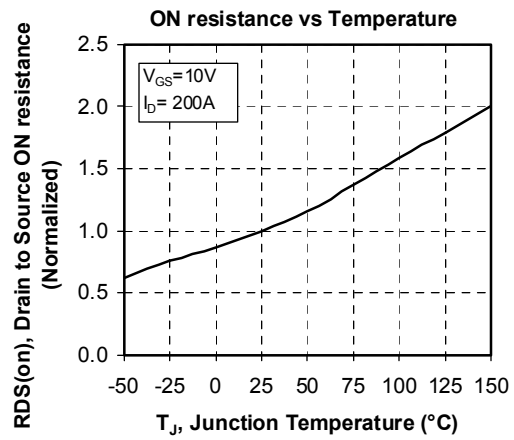
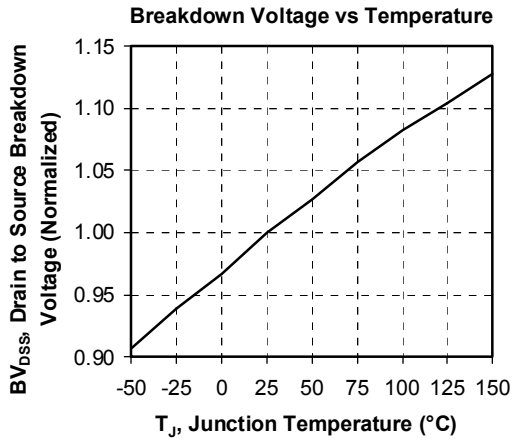
Source - Drain diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
I_S	Continuous Source current (Body diode)	$T_c = 25^\circ\text{C}$			495	A	
		$T_c = 80^\circ\text{C}$			370		
V_{SD}	Diode Forward Voltage	$V_{GS} = 0V, I_S = -400A$			1.3	V	
dv/dt	Peak Diode Recovery ^①				5	V/ns	
t_{rr}	Reverse Recovery Time	$I_S = -400A$ $V_R = 66V$ $di/dt = 400A/\mu\text{s}$	$T_j = 25^\circ\text{C}$			190	ns
			$T_j = 125^\circ\text{C}$			370	
Q_{rr}	Reverse Recovery Charge	$I_S = -400A$ $V_R = 66V$ $di/dt = 400A/\mu\text{s}$	$T_j = 25^\circ\text{C}$		1.6	μC	
			$T_j = 125^\circ\text{C}$		6.8		

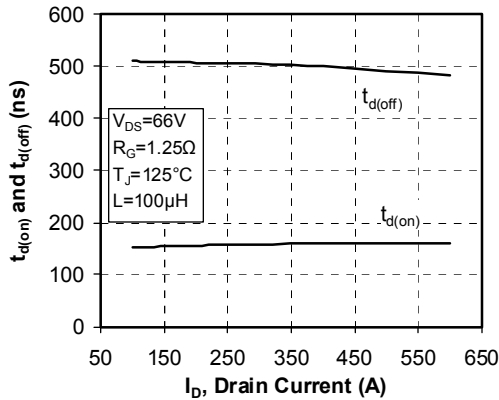
^① dv/dt numbers reflect the limitations of the circuit rather than the device itself.

$$I_S \leq -495A \quad di/dt \leq 400A/\mu\text{s} \quad V_R \leq V_{DSS} \quad T_j \leq 150^\circ\text{C}$$

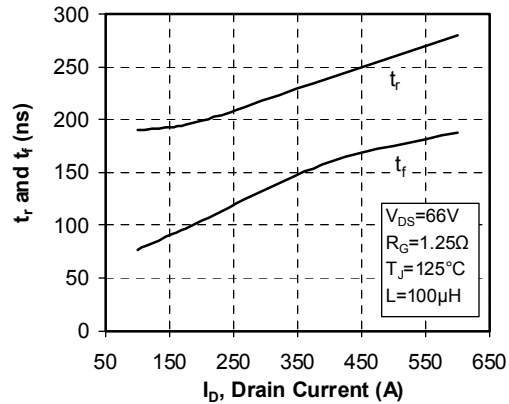
Typical Performance Curve




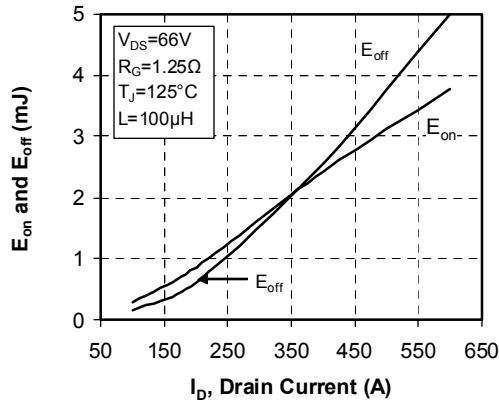
Delay Times vs Current



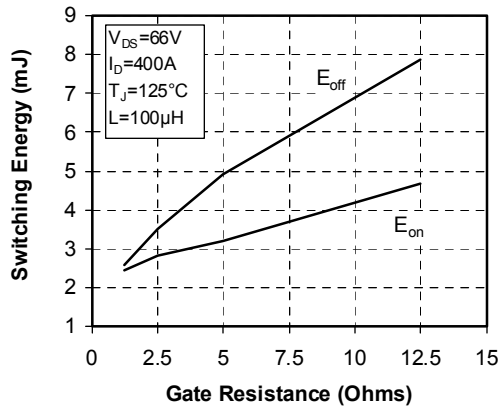
Rise and Fall times vs Current



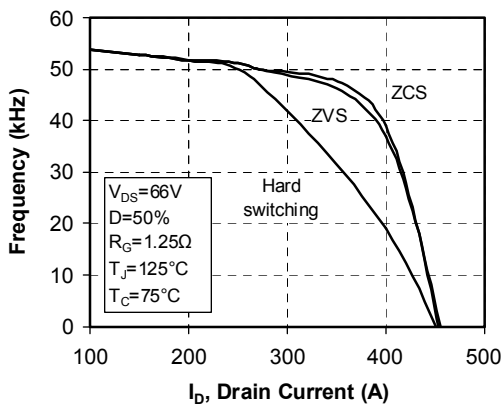
Switching Energy vs Current



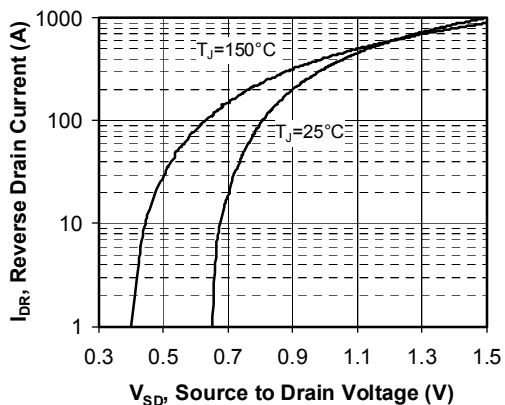
Switching Energy vs Gate Resistance



Operating Frequency vs Drain Current



Source to Drain Diode Forward Voltage



Microsemi reserves the right to change, without notice, the specifications and information contained herein

Microsemi's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. U.S. and Foreign patents pending. All Rights Reserved.